Quad 8-Bit CMOS D/A Converter with Internal 10 V Reference

DAC-8426

1.1 Scope.

This specification covers the detail requirement for a quad 8-bit CMOS digital-to-analog converter with output voltage amplifiers and internal 10 V voltage reference. The internal latches provide direct interface for most microprocessors. The DAC-8426 operates with either a dual or single power supply.

It is highly recommended that this data sheet be used as a baseline for new military or aerospace specification control drawings.

1.2 Part Number.

The complete part numbers per Table 1 of this specification is as follows:

Device	Part Number	Package
−1	DAC-8426AR/883	R

1.2.3 Case Outline.

Letter	Case Outline (Lead Finish per MIL-M-38510)
R	20-Lead Ceramic Dual-in-Line Package (Cerdip)

1.3 Absolute Maximum Ratings. (T_A = +25°C unless otherwise noted)

V_{DD} to AGND or DGND . . . . . −0.3 V, +17 V
V_{SS} to AGND or DGND . . . . . −7 V, V_{DD}
V_{DD} to V_{SS} . . . . . −0.3 V, +24 V
AGND to DGND . . . . . −0.3 V, +5 V
Digital Input Voltage to DGND . . . . . −0.3 V, V_{DD}
V_{REFOUT} to AGND . . . . . −0.3 V, V_{DD}
V_{OUT} to AGND . . . . . V_{SS}, V_{DD}
Power Dissipation to +75°C . . . . . 500 mW
Derate above 75°C by . . . . . 6.4 mW/°C
Operating Temperature Range . . . . . −55°C to +125°C
Junction Temperature Range (T_J) . . . . . −65°C to +150°C
Storage Temperature Range . . . . . −65°C to +150°C
Lead Temperature (Soldering 60 sec) . . . . . +300°C

1.5 Thermal Characteristics.

Thermal Resistance θ_{JC} = 7°C/W
θ_{JA} = 70°C/W max

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DAC-8426—SPECIFICATIONS

Table 1.

Test	Symbol	Device Types	Limits Min	Limits Max	Group A Subgroups	Conditions[1]	Units
Resolution	N	All	8		1, 2, 3	T_A = +25°C, −55°C & +125°C	Bits
Total Unadjusted Error	TUE	−1		±1	1, 2, 3	Includes Reference[2] T_A = +25°C, −55°C & +125°C	LSB
		−2		±2	1, 2, 3		
Relative Accuracy	INL	−1		±1/2	1, 2, 3	T_A = +25°C, −55°C & +125°C	LSB
		−2		±1	1, 2, 3		
Differential Nonlinearity	DNL	All		±1	1, 2, 3	Note 3; T_A = +25°C, −55°C & +125°C	LSB
Zero Scale Error	V_{ZSE}	All		20	1, 2, 3	V_{SS} = −5 V; T_A = +25°C, −55°C & +125°C	mV
Reference Output Voltage	V_{REFOUT}	−1	9.96		1, 2, 3	No Load; T_A = +25°C, −55°C & +125°C	V
		−2	9.92	10.08			
Reference Load Regulation	LD_{REG}	All		0.1	1, 2, 3	ΔI_L = 10 mA; T_A = +25°C, −55°C & +125°C	%/mA
Reference Line Regulation	LN_{REG}	All		0.04	1, 2, 3	ΔV_{DD} = ±10%; T_A = +25°C, −55°C & +125°C	%/mA
Reference Output Current	I_{REFOUT}	All	5		1, 2, 3	ΔV_{REFOUT} < 40 mV; T_A = +25°C, −55°C & +125°C	mA
Logic Input "0"	V_{INL}	All		0.8	1, 2, 3	T_A = +25°C, −55°C & +125°C	V
Logic Input "1"	V_{INH}	All	2.4		1, 2, 3	T_A = +25°C, −55°C & +125°C	V
Logic Input Current	I_{IN}	All		10	1, 2, 3	V_{IN} = 0 V or V_{DD}; T_A = +25°C, −55°C & +125°C	µA
Positive Supply Current[3]	I_{DD}	All		14	1, 2, 3	T_A = +25°C, −55°C & +125°C	mA
Negative Supply Current[3]	I_{SS}	All		10	1, 2, 3	Dual Supply, V_{SS} = −5 V; T_A = +25°C, −55°C & +125°C	mA
Power Supply Sensitivity	PSS	All		0.01	1, 2, 3	ΔV_{DD} = ±10%; T_A = +25°C, −55°C & +125°C	%/%
Output Source Current	I_{OUT}	All	10		1, 2, 3	Digital Inputs All Ones; T_A = +25°C, −55°C & +125°C	mA
Output Sink Current	I_{OUT-}	All	0.35		1, 2, 3	Digital Inputs All Zeros	mA
V_{OUT} Settling Time (Positive or Negative)	t_S	All		5	9	To ±1/2 LSB; T_A = +25°C	µs
Address to Write Setup Time	t_{AS}	All	0		9, 10, 11	T_A = +25°C, −55°C & +125°C	ns
Address to Write Hold Time	t_{AH}	All	0		9, 10, 11	T_A = +25°C, −55°C & +125°C	ns
Data Valid to Write Setup Time	t_{DS}	All	70		9, 10, 11	T_A = +25°C, −55°C & +125°C	ns
Data Valid to Write Hold Time	t_{DH}	All	10		9, 10, 11	T_A = +25°C, −55°C & +125°C	ns
Write Pulse Width	t_{WR}	All	50		9, 10, 11	T_A = +25°C, −55°C & +125°C	ns
Minimum Load Resistance	$R_{L(MIN)}$	All	2		1, 2, 3	Digital Inputs All Ones; T_A = +25°C, −55°C & +125°C	kΩ
V_{OUT} Slew Rate	SR	All	2.5		7	T_A = +25°C	V/µs

NOTES
[1]V_{DD} = +15 V ± 10%, AGND = 0 V, DGND = 0 V, V_{SS} = 0 V unless otherwise specified.
[2]Includes full-scale error, relative accuracy, and zero code error.
[3]Digital inputs V_{IN} = V_{INL} or V_{INH}; V_{OUT} and V_{REFOUT} unloaded.

Table 2. Electrical Test Requirements for Class B Devices

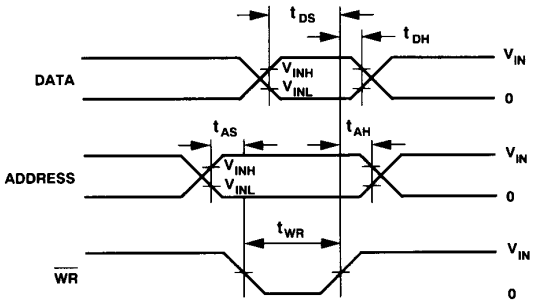
MIL-STD-883 Test Requirements	Subgroups (See Table 3)
Interim Electrical Parameters (Pre Burn-In)	1
Final Electrical Test Parameters	1,* 2, 3
Group A Test Requirements	1, 2, 3, 7, 9, 10, 11

NOTE
*PDA applies to Subgroup 1 only. No other subgroups are included in PDA.

Table 3. Control Table

Logic Control $\overline{WR}$	A1	A0	DAC-8426 Operation
H	X	X	No Operation Device Not Selected
L	L	L	DAC A Transparent
↓	L	L	DAC A Latched
L	L	H	DAC B Transparent
↓	L	H	DAC B Latched
L	H	L	DAC C Transparent
↓	H	L	DAC C Latched
L	H	H	DAC D Transparent
↓	H	H	DAC D Latched

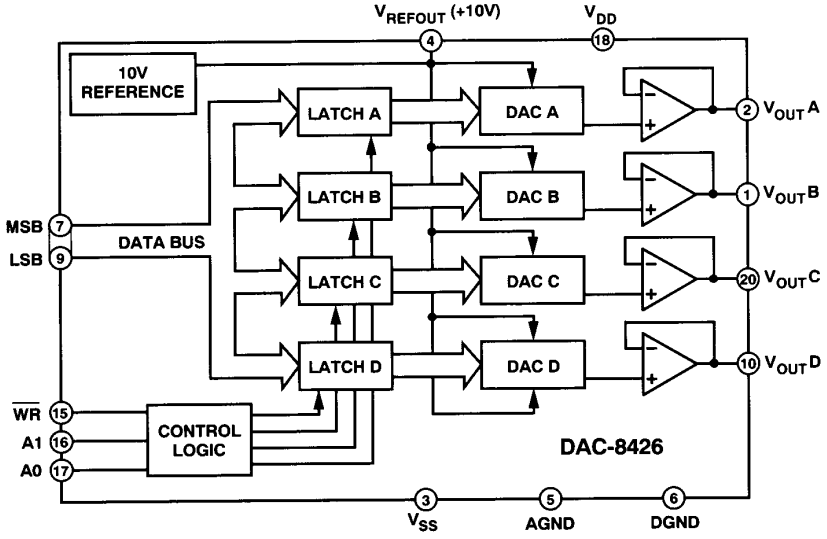
L = Low State, H = High State, X = Don't Care.

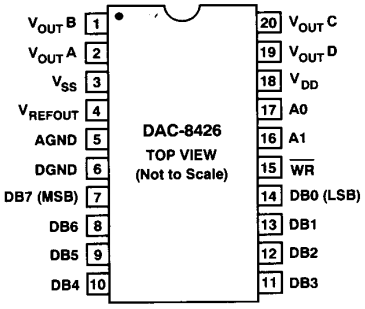


NOTES:
1. ALL INPUT SIGNAL RISE AND FALL TIMES ARE MEASURED FROM THE 10% TO 90% OF V_{DD} ($t_r = t_f$ = 20ns OVER THE V_{DD} RANGE)
2. TIMING REFERENCE LEVEL IS FROM $\frac{V_{INH} + V_{INL}}{2}$
3. V_{IN} = 5V

Write Timing Diagram

3.2.1 Functional Block Diagram and Terminal Assignments.



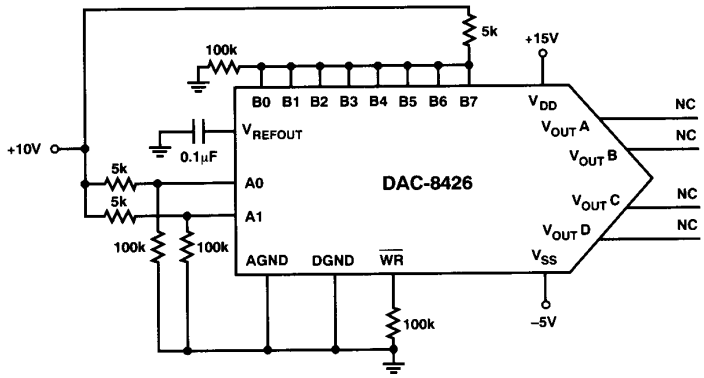


3.2.4 Microcircuit Technology Group.

This microcircuit is covered by technology group 80.

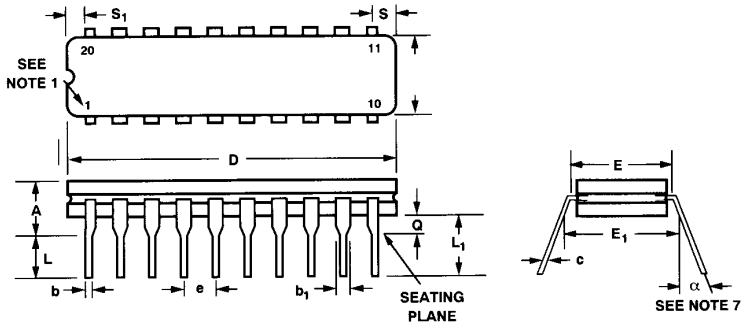
4.2.1 Life Test/Burn-In Circuit.

Steady state life test is per MIL-STD-883 Method 1005. Burn-in is per MIL-STD-883 Method 1015 test condition (B).



20-Lead Ceramic DIP

(R Suffix)



20-Lead Ceramic DIP
(R Suffix)

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A		0.200		5.08	
b	0.014	0.023	0.36	0.58	
b_1	0.030	0.070	0.76	1.78	2
c	0.008	0.015	0.20	0.38	
D		1.060		26.92	4
E	0.220	0.310	5.59	7.87	4
E_1	0.290	0.320	7.37	8.13	7
e	0.100 BSC		2.54 BSC		5
L	0.125	0.200	3.18	5.08	
L_1	0.150		3.81		
Q	0.015	0.060	0.38	1.52	3
S		0.080		2.03	6
S_1	0.005		0.13		6
α	0°	15°	0°	15°	

NOTES

1. Index area; a notch or a lead one identification mark is located adjacent to lead one.
2. The minimum limit for dimension b_1 may be 0.023″ (0.58 mm) for all four corner leads only.
3. Dimension Q shall be measured from the seating plane to the base plane.
4. This dimension allows for off-center lid, meniscus and glass overrun.
5. The basic lead spacing is 0.100″ (2.54 mm) between centerlines.
6. Applies to all four corners.
7. Leads center when α is 0°. E_1 shall be measured at the centerline of the leads.

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